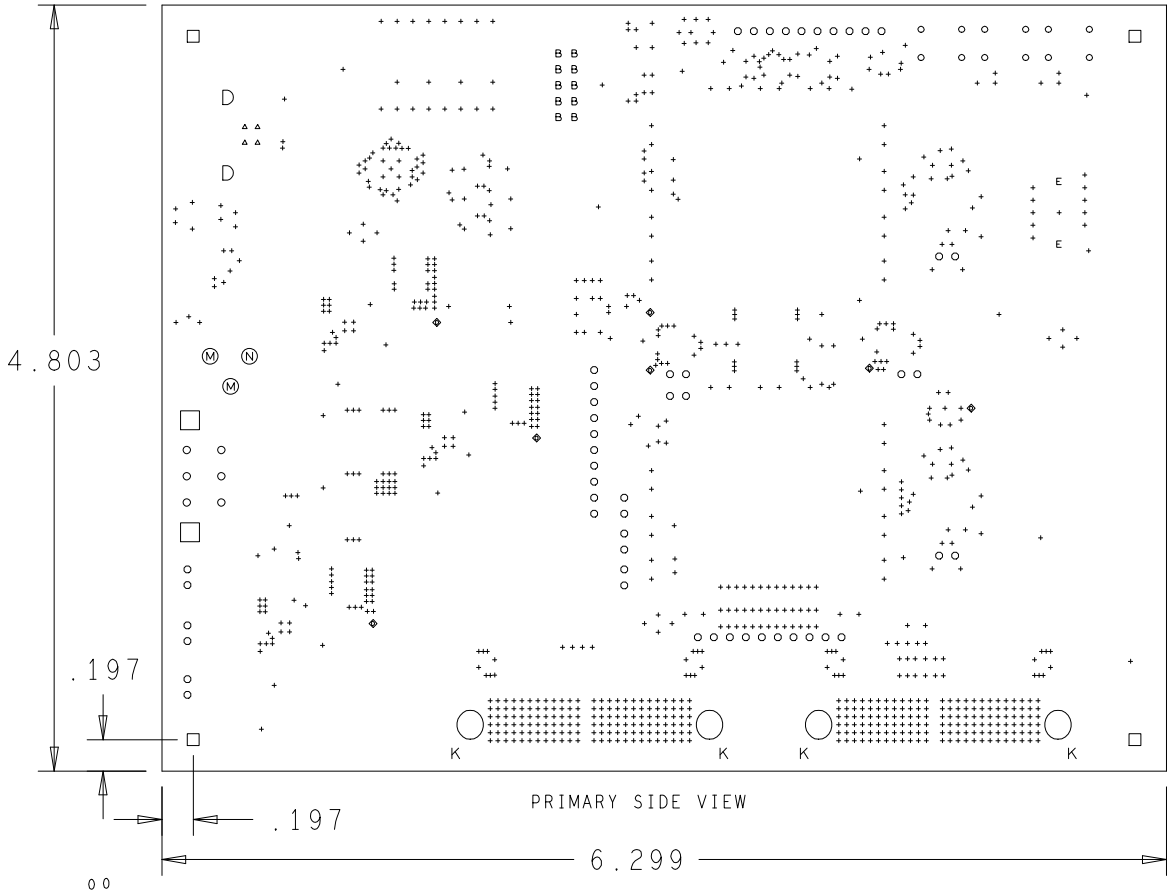


LAYER STACK-UP - ALL DIMENSIONS IN INCHES				
		50ohm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	90ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%	100ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
LAYER#	COPPER WEIGHT (oz)	TRACE WIDTH	TRACE WIDTH / SPACE	TRACE WIDTH / SPACE
LAYER 1 - PRIMARY SIDE - SIGNAL	HALF+PLATING	0.0048	0.00475/0.00725	
LAYER 2 - GROUND PLANE	H			
LAYER 3 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 4 - GROUND PLANE	H			
LAYER 5 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 6 - GROUND PLANE	H			
LAYER 7 - SIGNAL	H	0.005		0.004/ 0.005
LAYER 8 - GROUND PLANE	H			
LAYER 9 - SPLIT POWER PLANE	H			
LAYER 10 -SPLIT POWER PLANE	H			
LAYER 11 -GROUND PLANE	H			
LAYER 12 -SIGNAL	H	0.005		0.004/ 0.005
LAYER 13 -GROUND PLANE	H			
LAYER 14- SIGNAL	H	0.005		0.004/ 0.005
LAYER 15 -GROUND PLANE	H			
LAYER 16 -SIGNAL	H	0.005		0.004/ 0.005
LAYER 17 -GROUND PLANE	H			
LAYER 18- SECONDARY SIDE - SIGNAL	HALF+PLATING	0.0048		

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+0.0/-10.0	PLATED	2410
◆	30.0	+3.0/-3.0	PLATED	7
▲	36.0	+3.0/-3.0	PLATED	4
◦	40.0	+3.0/-3.0	PLATED	12
◌	42.0	+3.0/-3.0	PLATED	52
■	45.0	+3.0/-3.0	PLATED	10
◌	50.0	+3.0/-3.0	PLATED	6
D	90.0	+3.0/-3.0	PLATED	2
Ⓜ	120.0	+3.0/-3.0	PLATED	2
Ⓝ	140.0	+3.0/-3.0	PLATED	1
□	180.0	+3.0/-3.0	PLATED	4
E	40.0	+3.0/-3.0	NON-PLATED	2
K	66.0	+3.0/-3.0	NON-PLATED	4
□	118.0	+3.0/-3.0	NON-PLATED	2
○	182.0	+3.0/-3.0	NON-PLATED	4



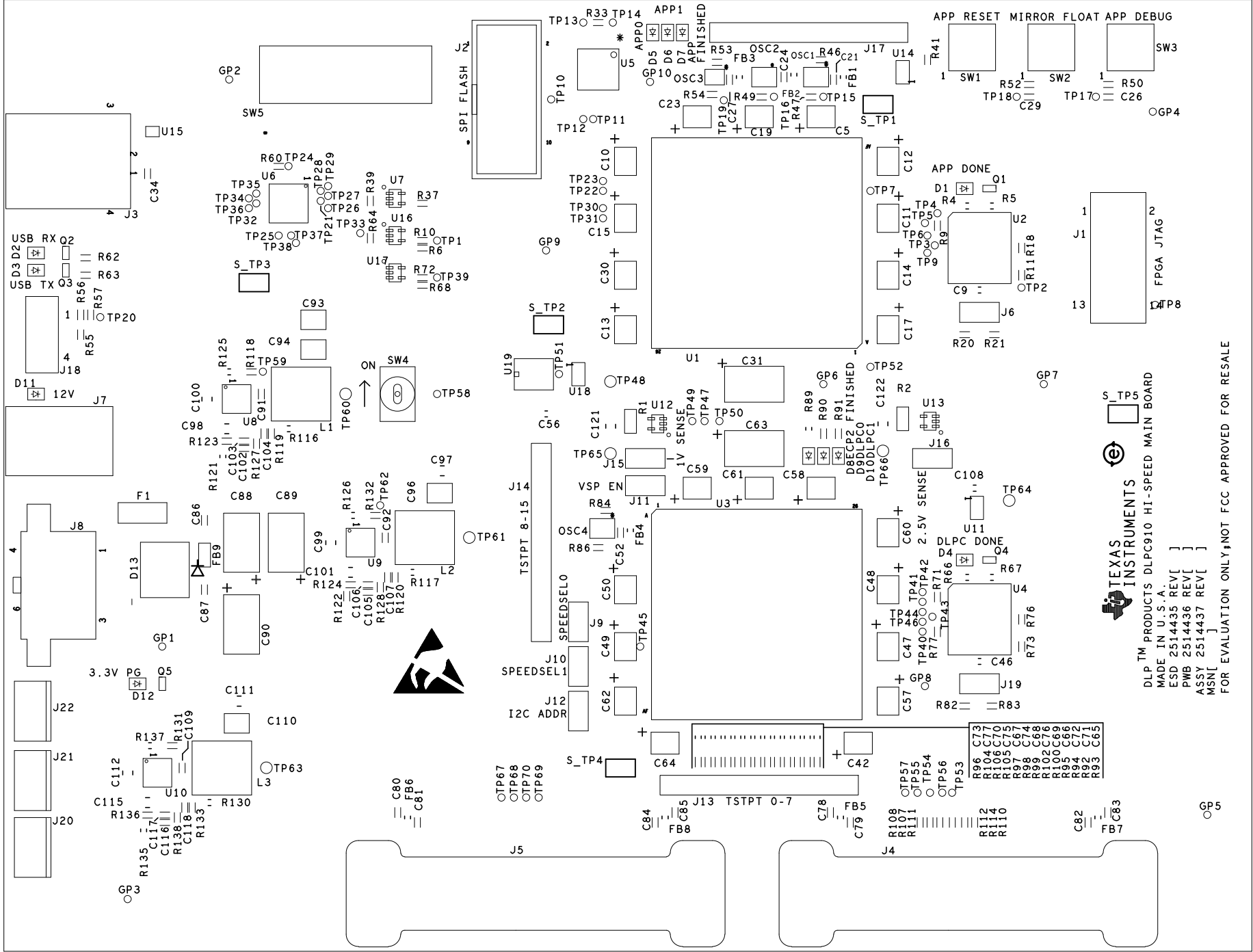
FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE HITACHI MCL-HE-679G OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
4. BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
6. OVERALL BOARD THICKNESS TO BE .095 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
9. PLATED THROUGH SLOT INDICATED WITH MULTIPLE DRILL HITS SHOULD BE FINISHED AS SMOOTH WALL BY VENDOR.
10. FABRICATOR SHOULD REMOVE ANY UNUSED PADS ON INTERNAL LAYERS.

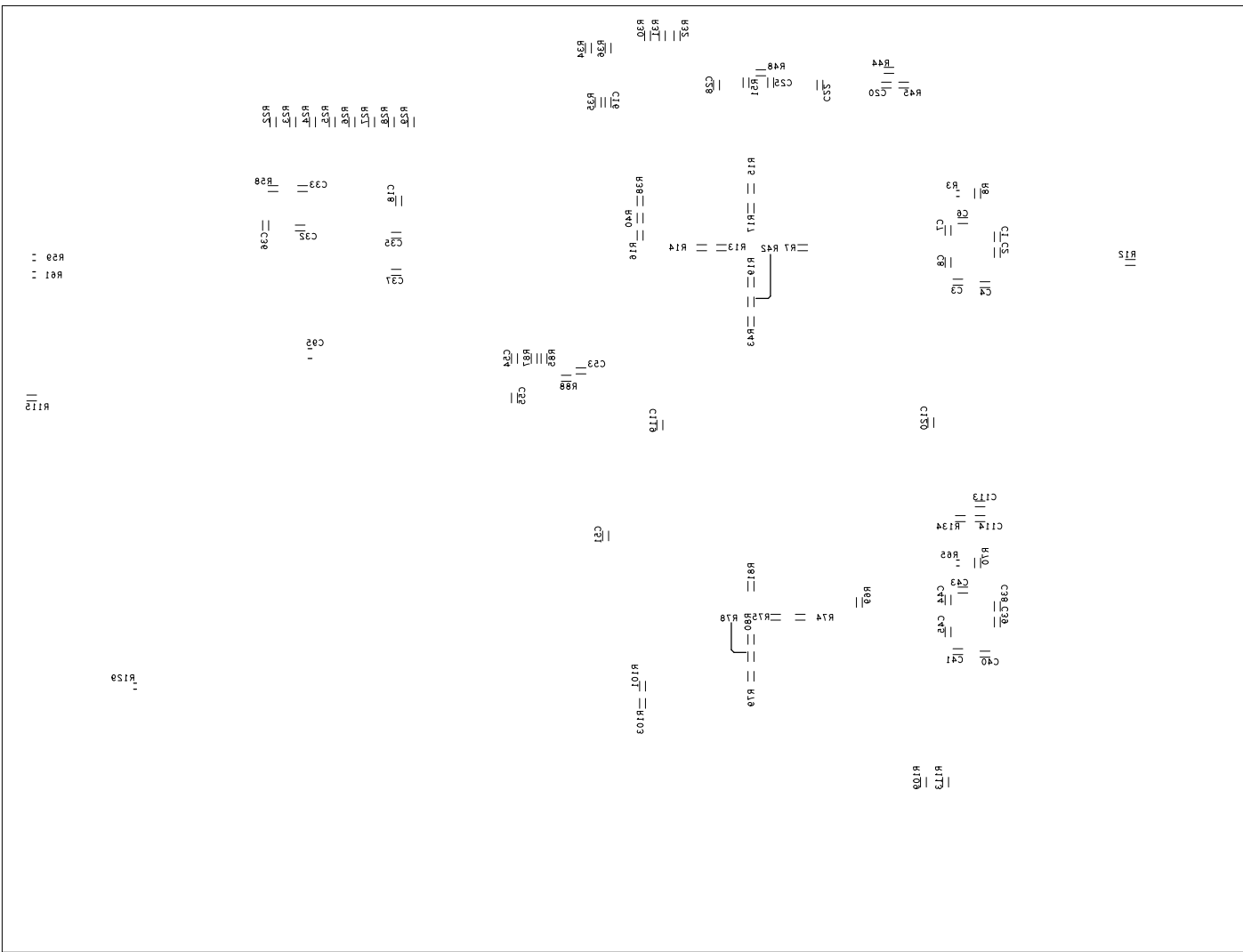
PROCESS NOTES:

1. EXCEPT AS NOTED BELOW, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 150 MICROINCHES THK MIN GOLD 5-15 MICROINCHES THK MIN.
1. PLATE ALL THE PAD AREAS OF J4 AND J5 TOP SIDE, WITH A MINIMUM OF 35 AND MAXIMUM 50 MICRO-INCHES OF ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 100 MICRO-INCHES OF ELECTROLYTIC NICKEL.
2. APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: GREEN. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
3. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
4. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME			DESCRIPTION		
DLPC910 HI SPEED MAIN BOARD			DRILL DRAWING		
BOARD NO.	REV	DATE	PRJ#	SH	OF
2514436	A	1-MAY-2015	TIDL-109433-01	25	25



CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME DLPC910 HI SPEED MAIN BOARD			DESCRIPTION SILKSCREEN - PRIMARY SIDE		
BOARD NO.	2514436	REV A	DATE 1-MAY-2015	PRJ# TIDL-109433-01	SH 21 OF 25



CUSTOMER NAME		TEXAS INSTRUMENTS			
BOARD NAME		DESCRIPTION			
DLPC910 HI SPEED MAIN BOARD		SILKSCREEN - SECONDARY SIDE			
BOARD NO.	2514436	REV	DATE	PRJ#	SH OF
		A	1-MAY-2015	TIDLPC-109433-01	22 25